## MMFTN20

## N-Channel Enhancement Vertical D-MOS Transistor

## Features

- High-speed switching
- No secondary breakdown


## Applications

- Thin and thick film circuits
- General purpose fast switching applications


1. Gate 2. Source 3. Drain SOT-23 Plastic Package


Absolute Maximum Ratings ( $\mathrm{T}_{\mathrm{a}}=25^{\circ} \mathrm{C}$ unless otherwise specified)

| Parameter | Symbol | Value | Unit |
| :--- | :---: | :---: | :---: |
| Drain-Source Voltage | $\mathrm{V}_{\mathrm{DS}}$ | 50 | V |
| Gate-Source Voltage (open drain) | $\mathrm{V}_{\mathrm{GSo}}$ | $\pm 20$ | V |
| Drain Current | $\mathrm{I}_{\mathrm{D}}$ | 100 | mA |
| Peak Drain Current | $\mathrm{I}_{\mathrm{DM}}$ | 300 | mA |
| Total Power Dissipation | $\mathrm{P}_{\mathrm{tot}}{ }^{1)}$ | 300 | mW |
|  | $\mathrm{P}_{\mathrm{tot}}{ }^{2)}$ | 250 | mW |
| Junction Temperature | $\mathrm{T}_{\mathrm{j}}$ | 150 | ${ }^{\circ} \mathrm{C}$ |
| Storage Temperature Range | $\mathrm{T}_{\text {stg }}$ | -65 to +150 | ${ }^{\circ} \mathrm{C}$ |

## Thermal Characteristics

| Parameter | Symbol | Value | Unit |
| :---: | :---: | :---: | :---: |
| Thermal Resistance from Juntion to Ambient | $R_{\text {өJA }}$ | $430^{1)}$ | $\mathrm{K} / \mathrm{W}$ |
|  | $\mathrm{R}_{\text {өJA }}$ | $500^{2)}$ | $\mathrm{K} / \mathrm{W}$ |

[^0]Characteristics at $\mathrm{T}_{\mathrm{a}}=25^{\circ} \mathrm{C}$ unless otherwise specified

| Parameter | Symbol | Min. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: |
| Drain-Source Breakdown Voltage at $I_{D}=10 \mu \mathrm{~A}$ | $\mathrm{V}_{\text {(BR) }{ }^{\text {dSS }}}$ | 50 | - | V |
| Drain-Source Leakage Current at $V_{D S}=40 \mathrm{~V}$ | $\mathrm{I}_{\text {DSS }}$ | - | 1 | $\mu \mathrm{A}$ |
| Gate-Source Leakage Current at $\mathrm{V}_{\mathrm{GS}}= \pm 20 \mathrm{~V}$ | IGss | - | $\pm 100$ | nA |
| Gate-Source Threshold Voltage at $V_{D S}=V_{G S}, I_{D}=1 \mathrm{~mA}$ | $\mathrm{V}_{\mathrm{GS}(\mathrm{th})}$ | 0.4 | 1.8 | V |
| $\begin{aligned} & \text { Drain-Source On-State Resistance } \\ & \text { at } \mathrm{V}_{G S}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=100 \mathrm{~mA} \\ & \text { at } \mathrm{V}_{G S}=5 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=100 \mathrm{~mA} \\ & \text { at } \mathrm{V}_{G S}=2.5 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=10 \mathrm{~mA} \end{aligned}$ | $\mathrm{R}_{\mathrm{DS} \text { (on) }}$ | - | $\begin{aligned} & 15 \\ & 20 \\ & 30 \end{aligned}$ | $\Omega$ |
| Forward Transfer Admittance at $\mathrm{V}_{\mathrm{DS}}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=100 \mathrm{~mA}$ | $\left\|y_{f s}\right\|$ | 40 | - | mS |
| Input Capacitance at $\mathrm{V}_{\mathrm{DS}}=10 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}$ | $\mathrm{C}_{\text {iss }}$ | - | 15 | pF |
| Output Capacitance at $\mathrm{V}_{\mathrm{DS}}=10 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}$ | $\mathrm{C}_{\text {oss }}$ | - | 15 | pF |
| Reverse Transfer Capacitance at $V_{D S}=10 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}$ | $\mathrm{C}_{\text {rss }}$ | - | 5 | pF |
| Turn-On Time at $\mathrm{V}_{\mathrm{GS}}=0$ to $10 \mathrm{~V}, \mathrm{~V}_{\mathrm{DD}}=20 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=100 \mathrm{~mA}$ | $\mathrm{t}_{\text {(on) }}$ | - | 5 | ns |
| Turn-Off Time at $\mathrm{V}_{\mathrm{GS}}=10$ to $0 \mathrm{~V}, \mathrm{~V}_{\mathrm{DD}}=20 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=100 \mathrm{~mA}$ | $\mathrm{t}_{\text {(off) }}$ | - | 10 | ns |

SEMTECH ELECTRONICS LTD.


[^0]:    ${ }^{1)}$ Device mounted on a ceramic substrate $10 \times 8 \times 0.7 \mathrm{~mm}$.
    ${ }^{2)}$ Device mounted on a printed-circuit board.

